



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification Number:	20260921000.0	Notification Issued	September 22, 2026
Datasheet for MSPM0C110x-Q1			

Change Type(s)	Data Sheet/Electrical Specification
ZVEI ID	SEM-DS-02, SEM-DS-03

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



MSPM0C1104-Q1, MSPM0C1103-Q1

SLASF93B – OCTOBER 2023 – REVISED SEPTEMBER 2026

Changes from August 30, 2024 to September 30, 2026 (from Revision A (August 2024) to Revision B (September 2026))

	Page
• Updated package options.....	1
• Added the Package Information table.....	2
• Added DSBGA package to Device Comparison	5
• Removed the DGS32 pin diagram, pin attributes, and signal descriptions.....	6
• Removed TIMx timer resolution bit specification.....	14
• Updated UART AGFSEL=0 suppressed pulse duration typ to 6ns.....	14
• Updated Temperature Sensor temperature coefficient min and typ specification.....	14
• Added Temperature Sensor test conditions for factory trim and temperature coefficient.....	14
• Added Timing Characteristics for tWAKE SLEEP1/2, tWAKE STBY0/1, tWAKE SHDN, tDELAY SLEEP1, tDELAY STOP0, tDELAY STBY0, and footnote (1).....	14
• Added Flash Memory Characteristics footnotes (1) and (3).....	14
• Added Flash Memory Characteristics t_ERASE (SEC) <2K and 10K cycles at 25C (Tj).....	14

• Updated Flash Memory Characteristics IDD_ERASE, IDD_PGM, t_PROG(WORD, 64), and t_PROG(SEC, 64).....	14
• Corrected Abs max sink & source current test condition for VDD and VSS from ambient to junction temperature.....	14
• Added SYSOSC footnotes indicating sysosc accuracy test conditions and removed SYSOSC footnote (2).....	14
• Added thermal characteristics for DSBGA-8 (YCJ).....	14
• Updated all IDDSTOP0, ULPCLK=4MHz max values at each temperature.....	15
• Added IDDSLEEP uA/MHz specification.....	15
• Updated IDDSLEEP at 125C max from 1680uA to 1370uA.....	15
• Removed footnote (1) indicating dVDD/dt ≤ 3V/s	16
• Updated VBOR+, COLD specification	16
• Updated Digital IO output rise and fall time max.....	20
• Updated Digital IO VOH and VOL min and max	20
• Removed ADC Linearity footnote (3).....	21
• Removed ADC Switching Characteristics sample time with VREF specification.....	21
• Added ADC Electrical Characteristics footnote (2)	21
• Updated VREF temperature coefficient to 80ppm/C max.....	23
• Updated I2C AGFSEL=0 suppressed pulse duration typ to 6ns.....	24
• Added SPI footnote (4).....	25
• Updated SPI controller tCS_LEAD, tCS_LAG, tCS_ACC, tCS_DIS, tSU_CI, tHD_CI and peripheral tCS_LEAD, tCS_ACC, tCS_DIS, tSU_PI specifications.....	25
• Added temperature sensor to Table 8-1	28
• Added table note 2 regarding proper NONMAIN configuration policy.....	31
• Updated perihperal naming from "NVMNW" to "FLASHCTL"	31
• Updated ADC0 Channel Mapping	34
• Added figure for the VREF module.....	35
• Added Security chapter.....	35
• Clarified the FIFO entries description.....	35
• Clarified the FIFO entries description.....	36
• Clarified the FIFO entries description.....	36
• Added Table 8-10	37
• Updated TIMA0 power domain to PD0 in Table 8-9	37
• Updated Figure 8-2 to include VREF	39
• Updated Section 8.23	40
• Updated Section 8.23	40
• Added the DEGUGSS section.....	41
• Added MSPM0C110xS8YCJR USERID.....	41
• Updated the typical application schematic and added link to the MSPM0 C-Series MCU HW Development Guide.....	43
• Added Documentation Support section.....	45

The datasheet number will be changing.

Device Family	Change From:	Change To:
MSPM0C110x-Q1	SLASF93A	SLASF93B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/MSPM0C1104-Q1>

Reason for Change:	To accurately reflect device characteristics
Anticipated impact on Form, Fit, Function, Quality or Reliability:	None
Changes to product	None

identification resulting from this PCN:	
--	--

Products Affected:		
M0C1104QDDFRQ1	M0C1104QRUKRQ1.B	M0C1104QDYRQ1.A
M0C1104QDGS20RQ1.A	M0C1103QDDFRQ1	M0C1104QDDFRQ1.A
M0C1104QDYRQ1	M0C1103QRUKRQ1.A	M0C1103QRUKRQ1
M0C1104QDSGRQ1.A	M0C1104QDSGRQ1.B	M0C1103QDGS20RQ1
M0C1103QDGS20RQ1.B	M0C1103QDDFRQ1.B	M0C1103QDYRQ1.A
M0C1104QDGS20RQ1.B	M0C1103QDYRQ1	M0C1104QRUKRQ1.A
M0C1103QRUKRQ1.B	M0C1104QDDFRQ1.B	M0C1104QDSGRQ1
M0C1103QDSGRQ1.A	M0C1103QDYRQ1.B	M0C1104QDYRQ1.B
M0C1103QDDFRQ1.A	M0C1103QDSGRQ1	M0C1103QDSGRQ1.B
M0C1104QDGS20RQ1	M0C1103QDGS20RQ1.A	M0C1104QRUKRQ1

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision

of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.